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DOCKET: FIS920030315US1

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

INVENTOR:	Edmund D. Blackshear	)	EXAMINER:	A. O. Williams
		)		
SERIAL NO.:	10/719,334	)	ART UNIT:	2826
		)		
FILING DATE:	November 21, 2003	)	DATE:	May 11, 2006
		)		
FOR:	OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME			

**AMENDMENT UNDER RULE 312**

**MAIL STOP ISSUE FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Notice of Allowance dated **March 13, 2006**, please amend the application as follows: